

# Bill of Materials

Package	Body Size	Material	FROM Carsem Malaysia	TO STATS ChipPAC Malaysia
LFCSP	5x5 mm	Die Attach	Sumitomo CRM1076DJ	Ablestik 3230
		Wire	1.0 mil	1.0 mil
		Mold Compound	Sumitomo E670C	Sumitomo G770
		Leadframe	C194	C194
	4x4 mm 3x3 mm	Die Attach	Sumitomo CRM1076DJ	Ablestik 8290
		Wire	1.0	1.0 mil
		Mold Compound	Sumitomo E670C	Sumitomo G770
		Leadframe	C194	C194